



## PRESS RELEASE

### PRESS RELEASE

GRENOBLE, (France), February 29, 2009

### **Léti and Brewer Science Create a Common Laboratory for New 3-D Stacking and MEMS Process Flows**

Léti and Brewer Science, Inc. signed a common lab agreement to combine their expertise in integration and materials into ultra-thin wafer processing flows for 3 Dimensional Packaging using Brewer Science temporary adhesives. They are also collaborating in the development of photosensitive and non-photosensitive coatings for MEMS manufacturing processes.

#### **A strengthened collaboration**

In October 2007, Léti and Brewer Science began the integration of WaferBond™ materials into 3-D chip stacking process flows to achieve reliable, user friendly processes for ultra-thin wafer handling and processing. These products are of great interest in the creation of TSV's. At the end of 2008, the first full integration process was successfully completed. "We have, in a very limited time, achieved and characterized Unity Aspect Ratio vias on seventy microns thick wafers" says Nicolas Sillon, the Head of the Laboratory for advanced packaging and 3-D integration at Léti. "The developed technology based on WaferBond™ materials will accelerate the 3-D chip stacking projects we have at Léti. WaferBond™ materials have already been included in 3-D functional demonstrators delivered to key Léti partners. The results we presented at the 10th Electronics Packaging Technology Conference EPTC last December in Singapore are a world premiere" he added.

"The partnership with Léti has been extremely beneficial in achieving these successes", says Tony Flaim, Chief Technology Officer at Brewer Science, Inc. "Léti works as a true partner, so we have jointly decided to strengthen and extend our collaboration in the framework of a 3-year, common lab." Under this agreement, leading edge Brewer Science specialty products will be used in 3-D integration and MEMS process flows.

#### **More functionality, less space, lower cost**

Focus will be on development and integration of photosensitive and non-photosensitive coatings into MEMS manufacturing processes, where high aspect ratios are mandatory, and on organic coating layers for advanced KrF and ArF photoresist processes.

"Introducing advanced, tailored products will provide a very competitive advantage in the development of innovative technologies for MEMS, their packaging and their integration-- the key core competencies of our department" adds André Rouzaud, Deputy VP Microsystems at Léti.

"3-D Packaging is becoming the next enabler in the industry's quest to achieve more functionality in less space for lower cost", asserts Lori Nye, Executive Director Marketing at Brewer Science. "And, new MEMS technologies provide automated interaction with the environment around us." The expanded effort between Léti and Brewer Science in the common lab will facilitate new breakthroughs.

---

Press contacts

## **CEA-LETI**

Clément Moulet, Press Officer

Tel: +334.38.78.03.26

E-mail : [clement.moulet@cea.fr](mailto:clement.moulet@cea.fr)

## **Brewer Science**

Doyle Edwards, Marketing Communications

Tel: +1-573-364-0300

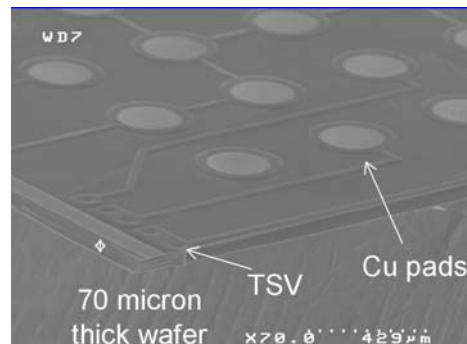
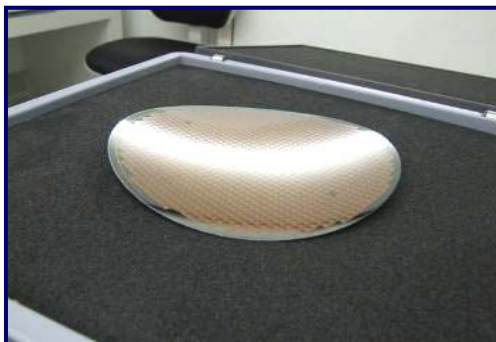
E-mail : [dedwards@brewerscience.com](mailto:dedwards@brewerscience.com)

## **About Brewer Science**

Brewer Science delivers innovative coating solutions for applications, including lithography, advanced packaging, MEMS, nanotechnology, optoelectronics and compound semiconductors. The inventor of the ARC<sup>®</sup> (anti-reflective coatings) products for the microlithography world, we continue to expand our scope with ProTEK<sup>®</sup> temporary etch protective coatings, WaferBOND<sup>™</sup> temporary bonding materials, and microelectronics-grade carbon nanotube solutions. Exceptional technical expertise and extensive semiconductor industry knowledge, combined with our world-class product and customer support, make Brewer Science a company that continually enhances value to the entire electronics industry.

## **About CEA-LETI:**

CEA-LETI, the Laboratory for Electronics & Information Technology is operated by Direction de la Recherche Technologique at CEA, the French Atomic Energy Commission. It mainly aims at helping companies to increase their competitiveness through technological innovation and transfer of its technical know-how to industry. Major player in the MINATEC Micro-Nano technologies innovation center, CEA-LETI benefits from 8000 m<sup>2</sup> state-of-the-art clean rooms, with equipment worth some 160 million euros. It is currently employing some 1600 people among whom 1100 CEA employees and co-workers of various status including 100 people from industrial partners, working in the CEA-LETI premises within the framework of bilateral collaborations. Overall, research contracts with industry are worth 75% of CEA-LETI annual income. It has a very important patents portfolio, and filed last year more than 200 patents and 700 publications. The laboratory is structured into six departments, with a specific department operating 24-7 the technological facilities of the silicon technology platform, and five program-oriented programs covering the field of microelectronics, microsystems, optronics, sytem design and telco, and technologies for bio and health. For more information, visit [www.leti.fr](http://www.leti.fr)



*70 μm thick wafer with medium density TSV*

